

APPROVAL SHEET

To :

Customer P/N :

UDE P/N : SZ20-ZZ-0006

Description : QSFP28 Cage 1X2(Style A)

Press-fit

With heatsink & With Lightpipe

QSFP28 100G(NRZ), QSFP56 200G(PAM4)



Spec No.
SZ2021010-00

Update Date
2021/6/2

Revision
A

Approved	Checked	Prepared



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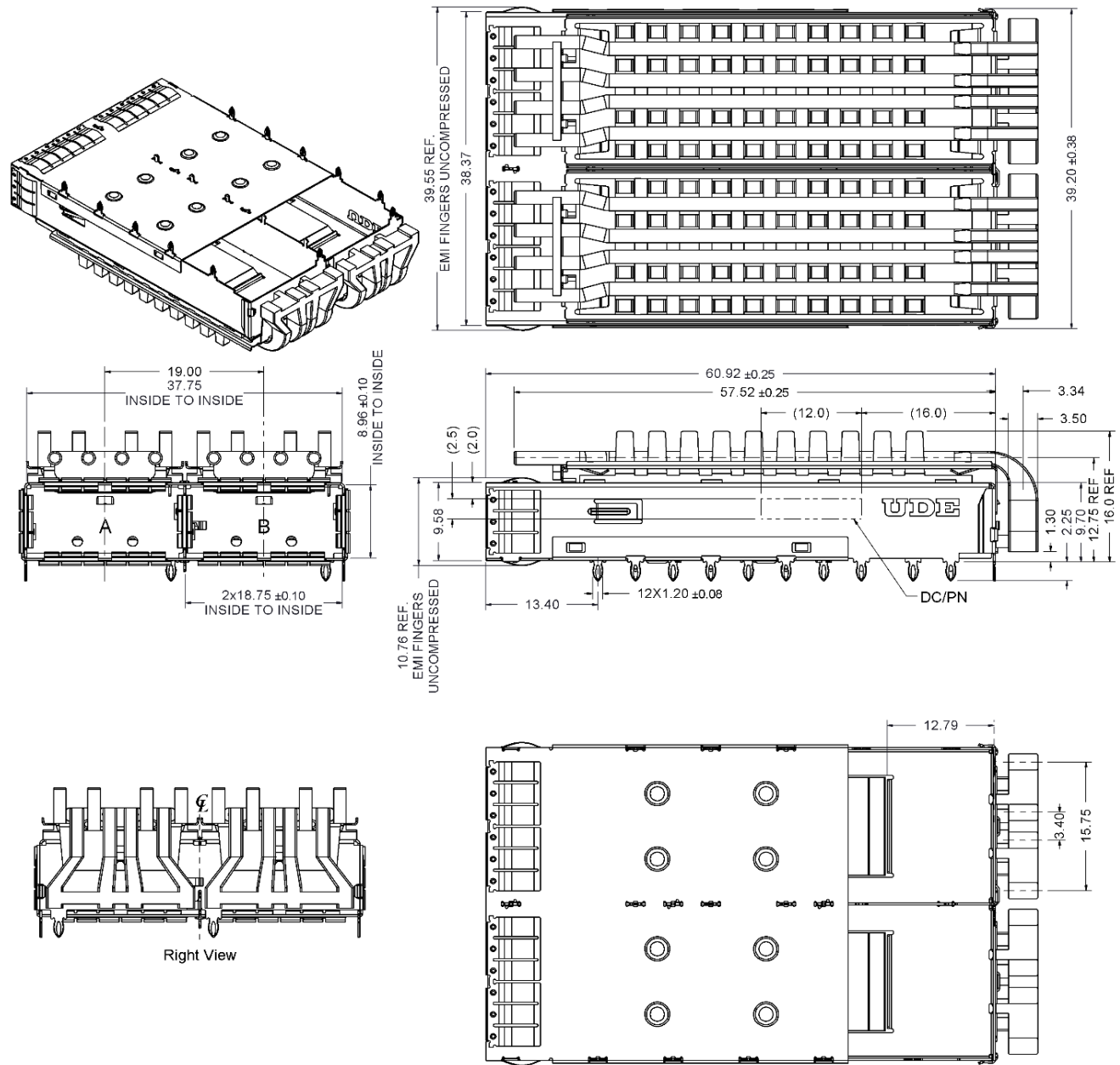
Revision History

[illegible]

1. MECHANICAL DIMENSION

Product Dimension

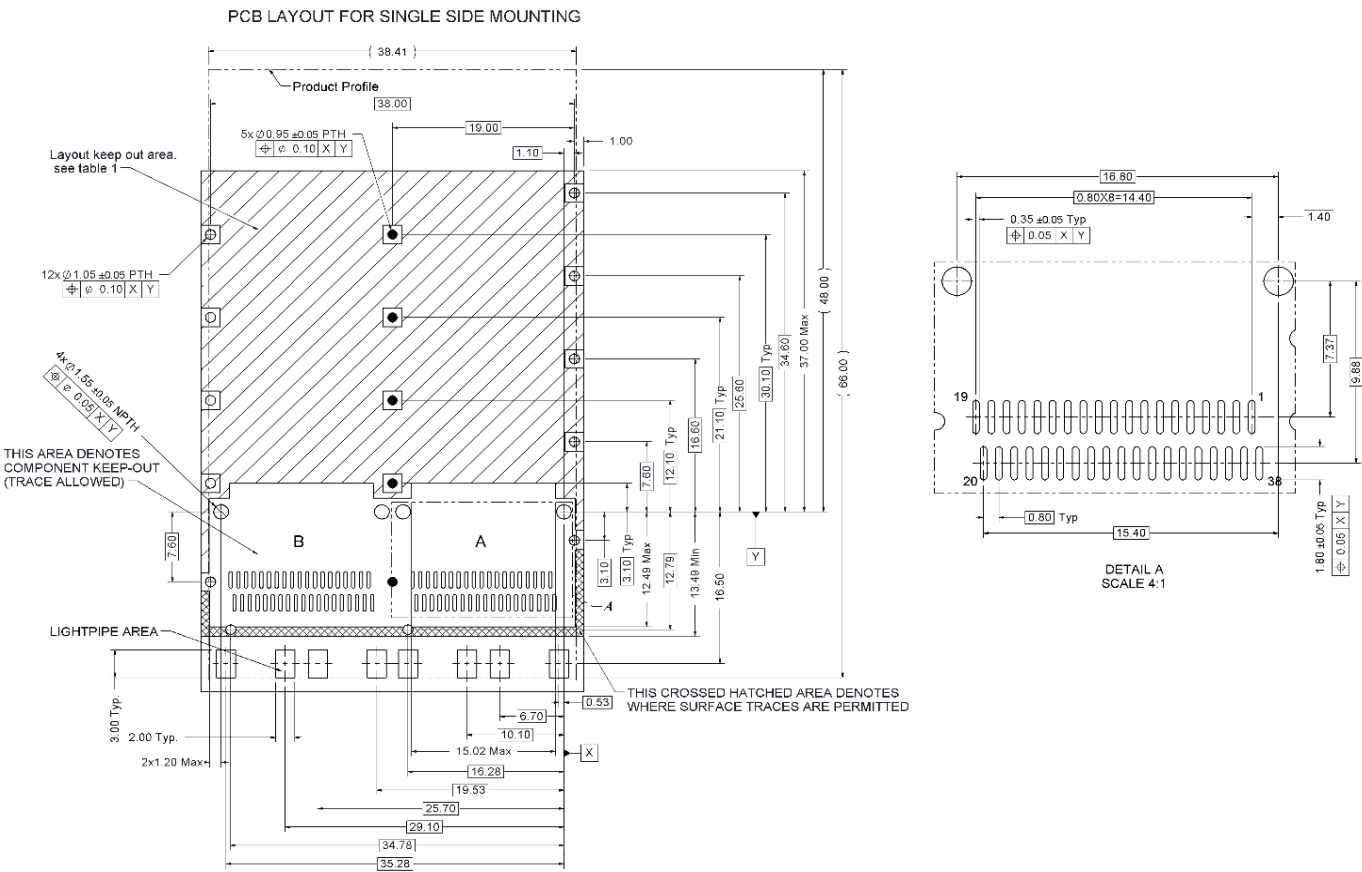
Unit:mm	General Tolerance :	X.X : ± 0.38
		X.XX : ± 0.20



2. Recommended PCB Layout.Component Side of Board

All dimension units are "mm".

All dimension tolerances are $\pm 0.05\text{mm}$ unless otherwise specified



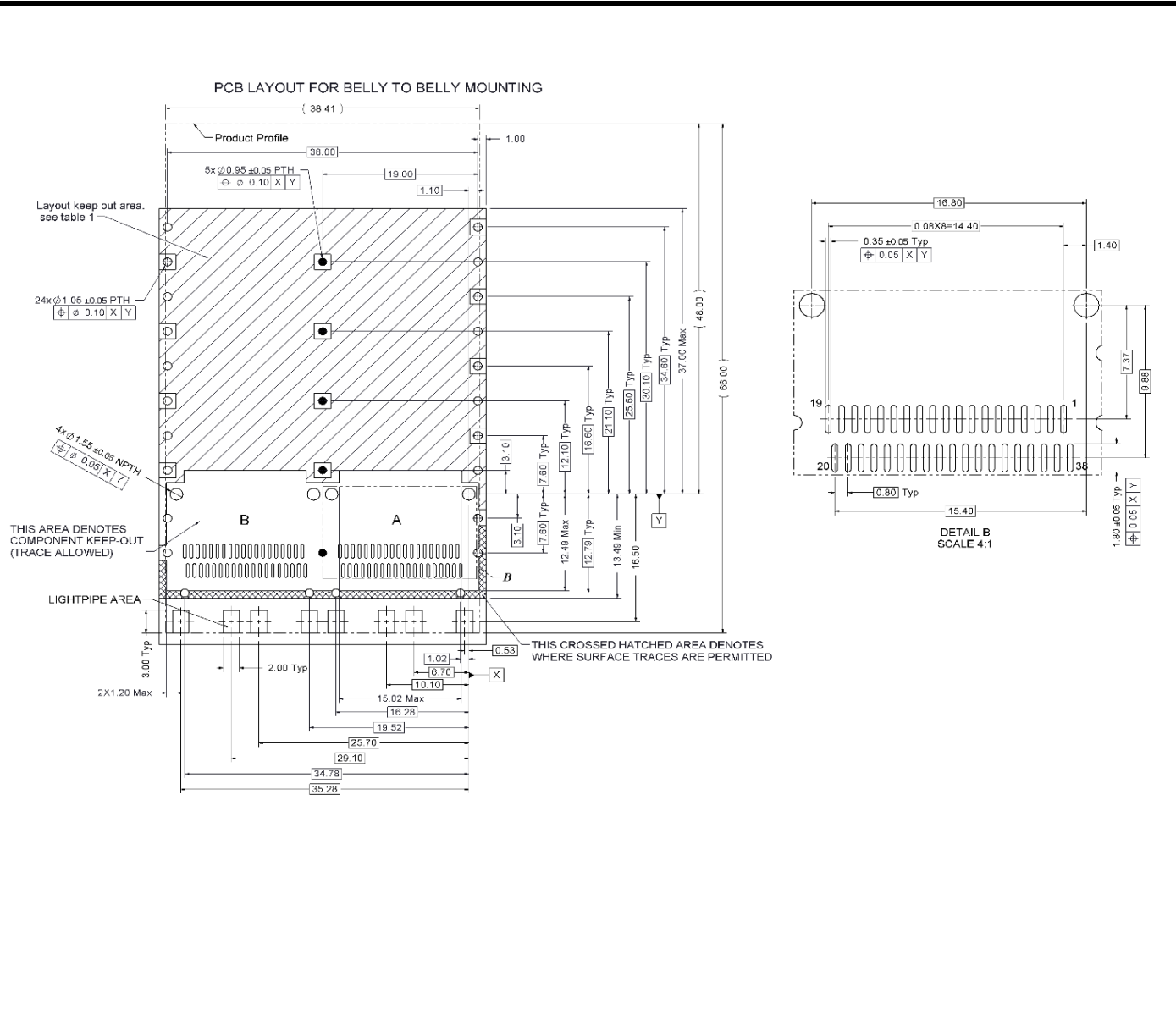
NOTES:

- 1.PADS AND VIAS CONNECT TO CHASSIS GROUND
RECOMMEND PADS TO BE 2.00mm SQUARE
- 2.RECOMMENDED THRU HOLE PLATING INCLUDES HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)
- 3.1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USE.

Table1

Layout Layer	Trace	component	Grounding	Test Point	Via Hole	PTH	NPTH
Component side	X	X	O	X	X	X	O
Inner layer	O	NA	O	NA	O	X	O
Bottom side	O	O	O	O	O	X	O

X--Forbid; O--OK; NA--Not Applicable.

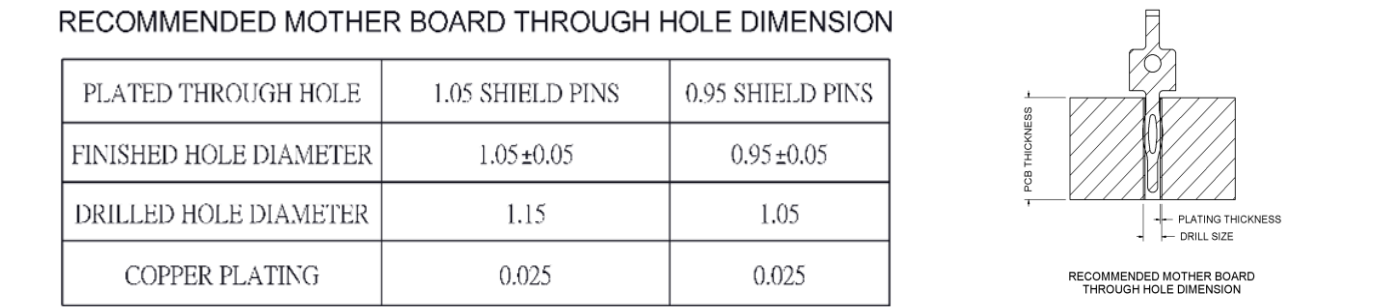


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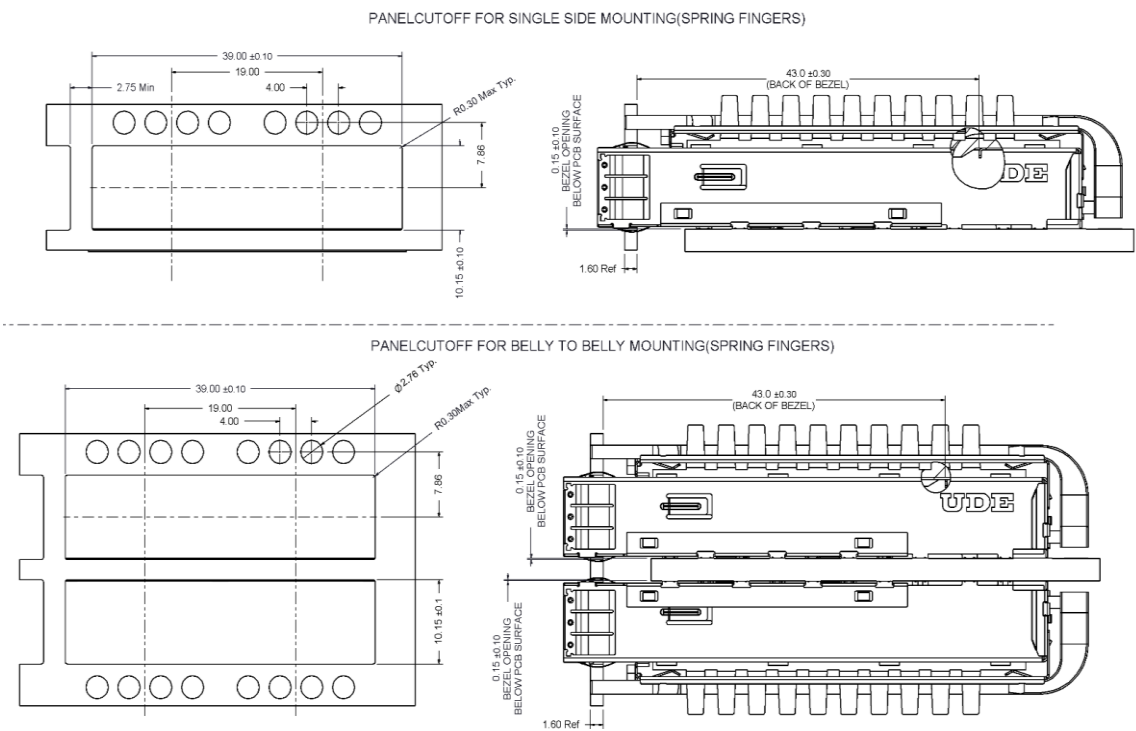
- 1.PADS AND VIAS CONNECT TO CHASSIS GROUND
RECOMMEND PADS TO BE 2.00mm SQUARE
- 2.RECOMMENDED THRU HOLE PLATING INCLUDES HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)
- 3.3.00mm MINIMUM PCB THICKNESS FOR BELLY TO BELLY SIDED USE.

RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

PLATED THROUGH HOLE	1.05 SHIELD PINS	0.95 SHIELD PINS
FINISHED HOLE DIAMETER	1.05±0.05	0.95±0.05
DRILLED HOLE DIAMETER	1.15	1.05
COPPER PLATING	0.025	0.025



3. Recommended Panel cutout



PRESS-FIT ASSEMBLIES

Hand place using proper seating force to engage all Leg tails into plated thru-holes.

Assemblies are to be seated per the instructions associated with the appropriate insertion tool

Note:UDE recommends only one connector assembly be installed at a time.

ASSEMBLE INSERTION FORCE		
PORT SIZE	PCB FINISH	FORCE
1X2	Copper w/OSP	210±30N

4. Packing Information
- 10 pcs finished goods per tray
 - 6 trays(60pcs finished goods) per master carton

5. REQUIREMENTS

Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

Material

Shield Parts

Top Shell : Copper Alloy, Thickness=0.25mm

Finish : 30 μ " min. Nickel

Bottom Shell : Copper Alloy, Thickness=0.25mm

Finish : 30 μ " min. Nickel

Mid Ground : Copper Alloy, Thickness=0.25mm

Finish : 30 μ " min. Nickel

EMI Spring Finger : Ph.Bronze, Thickness=0.06mm

Finish : 30 μ " min. Nickel

Heatsink Clip: SUS304, Thickness=0.20mm

Heatsink: Aluminum Alloy

Finish : Anodic oxidation, Natural Colour

Plastic Parts

Lightpipe : PC, Transparent, UL94V-0

6. Operating and Storage Temperature

Operating Temperature : -40°C to +85°C

Storage Temperature : - 55°C+105°C

7. QSFP CAGE specifications

Insertion force: 60 N max at a max. rate of 25.4mm per minute

(QSFP module to PCB connector and QSFP cage)

Extraction force :30 N max at a max. rate of 25.4mm per minute

(QSFP module to PCB connector and QSFP cage)

Cage Retention (Latch strength) : 125N Min.

Durability : 100 cycles for standard class

8. Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table.

All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

9. Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.